

2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.3. Specifications are subject to change without notice.

SPECIFICATION CS63CUV405C

PACKAGE OUTLINES Cathode Mark 0.4 Cathode Mark Resin-LED DIE-Soldering 1.0 1.0 0.6 Terminal 0.3 **Recommended Pad Layout** Notes: 1. All dimensions are in millimeters (inches).

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CS63CUV405C	InGaN	UV	Water Clear	150°





ABSOLUTE MAXIMUM RATINGS

 $(TA=25^{\circ}C)$

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lr	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

 $(TA=25^{\circ}C)$

Darameter	Symbol	Toot Condition	Value			Lloit
Parameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	1.0	4.2	1	mcd
Forward Voltage	VF	IF = 20mA	-	3.2	3.7	V
Reverse Leakage Current	lr	V _R = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	150	-	Deg
Wavelength at Peak Emission	λ P	IF = 20mA	-	405	-	nm

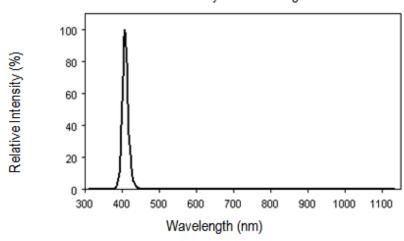
^{*}Tolerance of viewing angle: -10 / +5 deg.



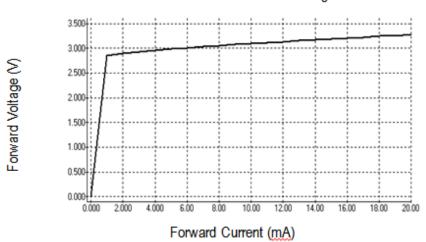


OPTICAL CHARACTERISTIC CURVES

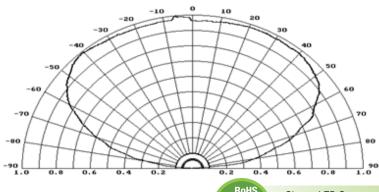
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



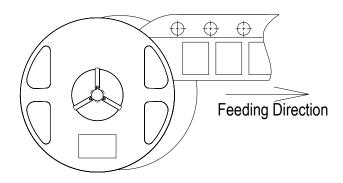
Directive Characteristics



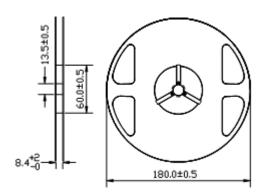


PACKAGING SPECIFICATION

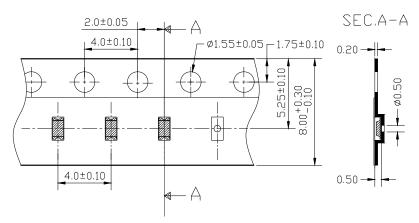
Feeding Direction



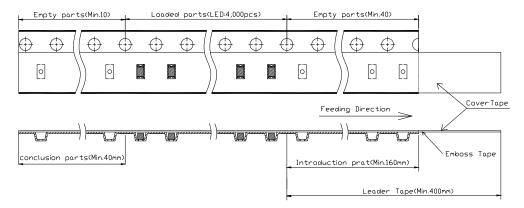
Dimensions of Reel (unit: mm)



Dimensions of Tape (unit: mm)



Arrangement of Tape



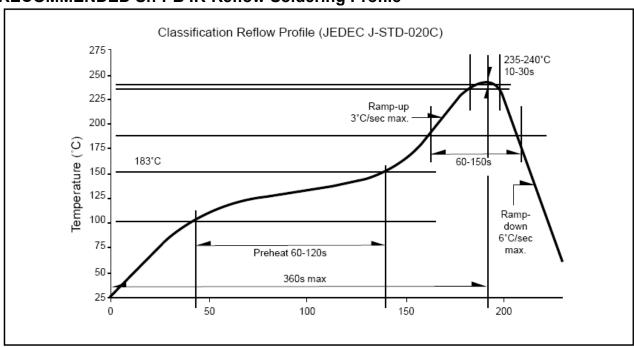
- 1. Empty component pockets are sealed with top cover tape
- 2. The maximum number of missing lamps is two
- 3. The cathode is oriented towards the tape sprocket hole
- 4. 4,000 pcs/Reel





SOLDERING CONDITIONS

RECOMMENDED Sn-PB IR-Reflow Soldering Profile



RECOMMENDED Pb-Free Soldering Profile

